

# CEM4948-VB Datasheet Dual P-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A) <sup>d, e</sup>	Q <sub>g</sub> (Typ.)		
- 60	0.054 at V <sub>GS</sub> = - 10 V	- 5.3	17 nC		
- 60	0.060 at V <sub>GS</sub> = - 4.5 V	- 5.0	17 110		

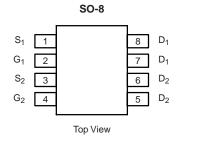
#### FEATURES

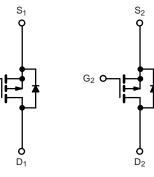
- Halogen-free
- Trench Power MOSFET
- 100 % UIS Tested

#### APPLICATIONS

Load Switches







P-Channel MOSFET

G1 0

P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_A$	= 25 °C, unless othe	erwise noted			
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V <sub>DS</sub>	- 60	V		
Gate-Source Voltage		V <sub>GS</sub>	± 20	v	
	T <sub>C</sub> = 25 °C		- 5.3 <sup>e</sup>		
Continuous Drain Current ( $T_1 = 150 \ ^{\circ}C$ )	T <sub>C</sub> = 70 °C		- 5.0 <sup>e</sup>		
Continuous Drain Current $(T_j = 150 \text{ C})$	T <sub>A</sub> = 25 °C	I <sub>D</sub>	- 5.3 <sup>a, b</sup>		
	T <sub>A</sub> = 70 °C		- 5.0 <sup>a, b</sup>	•	
Pulsed Drain Current	I <sub>DM</sub>	- 32 <sup>e</sup>	— A		
Quality of the Design Divide Quarter	T <sub>C</sub> = 25 °C		- 4.1		
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	- 2.0 <sup>a, b</sup>		
Avalanche Current	1 0.4 ml l	I <sub>AS</sub>	- 20		
Single-Pulse Avalanche Energy	L = 0.1 mH	E <sub>AS</sub>	20	mJ	
	T <sub>C</sub> = 25 °C		4.0		
Manimum Davies Disais stics	T <sub>C</sub> = 70 °C		2.5	10/	
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	– P <sub>D</sub> –	2.0 <sup>a, b</sup>	W	
	T <sub>A</sub> = 70 °C	1 -	1.4 <sup>a, b</sup>		
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>a, c</sup>	t ≤ 10 s	R <sub>thJA</sub>	38	50	°C/W	
Maximum Junction-to-Foot	Steady State	R <sub>thJF</sub>	20	25	0/10	

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. t = 10 s.

c. Maximum under Steady State conditions is 85  $^{\circ}\text{C/W}.$ 

d. Based on T<sub>C</sub> = 25 °C.

e. Limited by package.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = - 250 μA	- 60			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I <sub>D</sub> = - 250 μA		- 31			
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	i <sub>D</sub> = - 250 μA		4.5		mV/°C	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$	- 1.0		- 3.0	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zana Cata Maltana Duain Cumant	I <sub>DSS</sub>	$V_{DS} = -30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			- 1	μA	
Zero Gate Voltage Drain Current		$V_{DS} = -30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 \text{ °C}$			- 5		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge -10 \text{ V}, \text{ V}_{GS} = -10 \text{ V}$	- 30			А	
		V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 5 A	0.054				
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 4.5 A		0.060		Ω	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 10 V, I <sub>D</sub> = - 5 A		23		S	
Dynamic <sup>b</sup>				1			
Input Capacitance	C <sub>iss</sub>			1345			
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = - 15 V, V <sub>GS</sub> = 0 V, f = 1 MHz		210		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			180			
Total Gate Charge	Qg	V <sub>DS</sub> = - 15 V, V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 5 A		32 5	50	-	
				15	25		
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = -15 \text{ V}, \text{ V}_{GS} = -4.5 \text{ V}, \text{ I}_{D} = -5 \text{ A}$		4		nC	
Gate-Drain Charge	Q <sub>gd</sub>			7.5		1	
Gate Resistance	R <sub>g</sub>	f = 1 MHz		5.8		Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			10	15		
Rise Time	t <sub>r</sub>	V <sub>DD</sub> = - 15 V, R <sub>L</sub> = 15 Ω		8	15		
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D \cong$ - 1 A, $V_{GEN}$ = - 10 V, $R_q$ = 1 $\Omega$		45	70		
Fall Time	t <sub>f</sub>			12	25		
Turn-On Delay Time	t <sub>d(on)</sub>			42	70	ns	
Rise Time	t <sub>r</sub>	V <sub>DD</sub> = - 15 V, R <sub>L</sub> = 15 Ω		35	60		
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D \cong$ - 1 A, $V_{GEN}$ = - 4.5 V, $R_q$ = 1 $\Omega$		40	70		
Fall Time	t <sub>f</sub>	Ŭ		16	30		
Drain-Source Body Diode Characterist	ics			1			
Continous Source-Drain Diode Current	۱ <sub>s</sub>	T <sub>C</sub> = 25 °C			- 4.1		
Pulse Diode Forward Current	I <sub>SM</sub>				- 32	A	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = - 2 A, V <sub>GS</sub> = 0 V		- 0.75	- 1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			34	60	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			22	40	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = -2 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, \text{T}_J = 25 \text{ °C}$		11			
Reverse Recovery Rise Time	t <sub>b</sub>	1		23		ns	

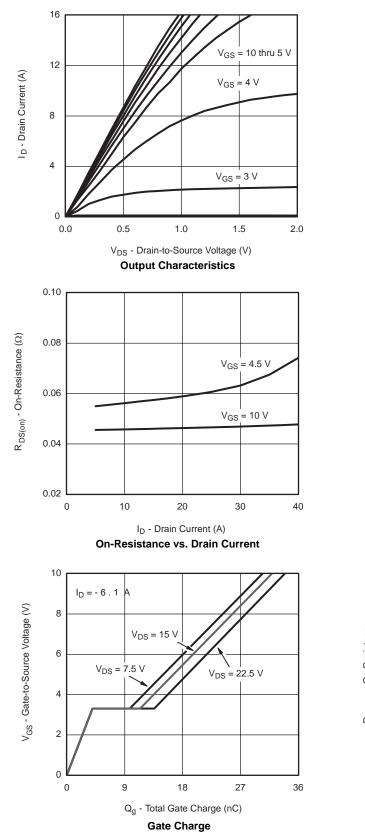
Notes:

a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

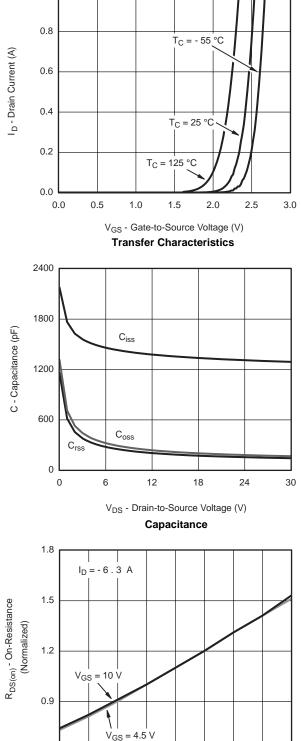
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





#### TYPICAL CHARACTERISTICS 25 C, unless otherwise noted



1.0

0.6

- 50

- 25

0

25

50

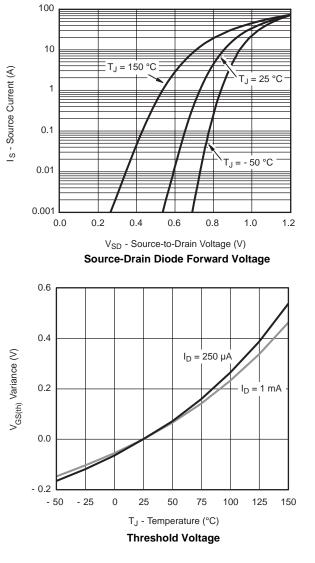
T<sub>J</sub> - Junction Temperature (°C) On-Resistance vs. Junction Temperature

75

100

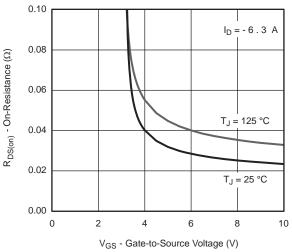
125 150



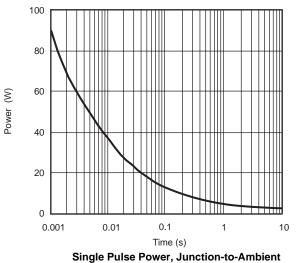


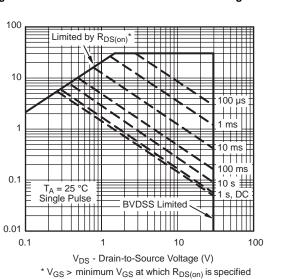
I<sub>D</sub> - Drain Current (A)

## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



On-Resistance vs. Gate-to-Source Voltage

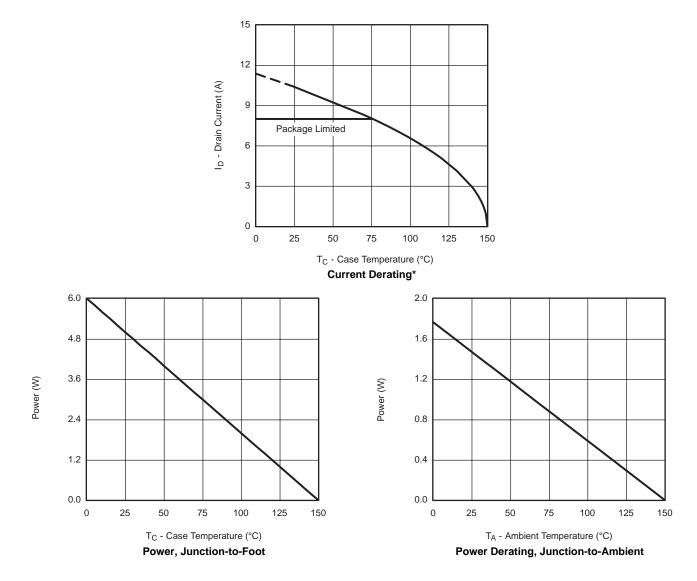




Safe Operating Area



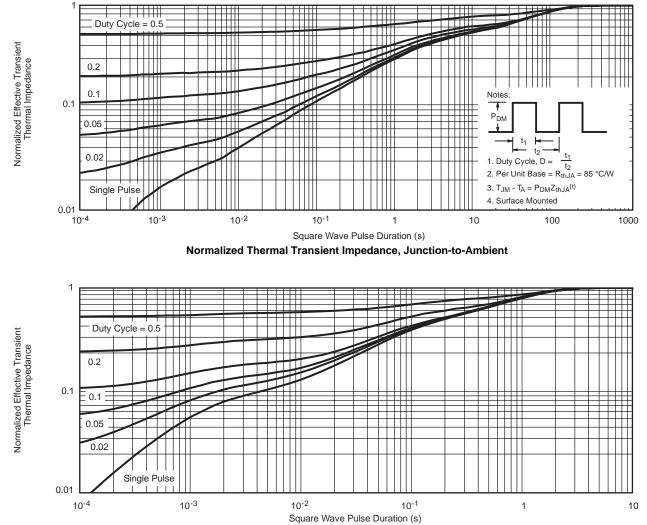
#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



\* The power dissipation  $P_D$  is based on  $T_{J(max)}$  = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Foot



## SOIC (NARROW): 8-LEAD

JEDEC Part Number: MS-012





	MILLIM	ETERS	INCHES			
DIM	Min	Мах	Min	Max		
A	1.35	1.75	0.053	0.069		
A <sub>1</sub>	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
E	3.80	4.00	0.150	0.157		
е	1.27	BSC	0.050 BSC			
н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498						



**RECOMMENDED MINIMUM PADS FOR SO-8** 



Recommended Minimum Pads Dimensions in Inches/(mm)



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